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(54) **ELECTRONIC-COMPONENT CARRIER BOARD AND A WIRING METHOD FOR THE SAME**

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(57) **ABSTRACT**

An electronic-component carrier board includes carrier plates formed in a stack, and insulating layers each disposed between two adjacent ones of the carrier plates. Multiple conductive pins extend through the insulating layers and the carrier plates. Multiple conductive wires equal in length and width are provided. Each conductive wire is connected to one of the conductive pins, covered by one of the insulating layers, disposed between two adjacent ones of the carrier plates, and extends outwardly from the stack of the carrier plates. A wiring method for the electronic-component carrier board is also disclosed.